at least one ceramic paste present in film form; and

blunting edges of the [sensing element] composite arrangement before sintering to increase a thermal shock resistance of the sensing element.

14. (Amended) The method according to claim 13, wherein the step of blunting includes the step of blunting the edges of the [sensing element] composite arrangement by shaping.

15. (Amended) The method according to claim 14, wherein the step of blunting the edges of the [sensing element] composite arrangement further includes the step of blunting the edges of the [sensing element] composite arrangement by stamping.

16. (Amended) The method according to claim 13, further comprising the step of:

introducing a profile into a stamping apparatus for pre-pressing a laminate construction of unsintered films of the [sensing element] composite arrangement.

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19. (Amended) The method according to claim 13, wherein the step of blunting the edges of the [sensing element] composite arrangement further includes the step of blunting the edges of the [sensing element] composite arrangement using a laser treatment.

20. (Amended) The method according to claim 13, wherein the step of blunting includes the step of blunting the edges of the [sensing element] composite arrangement using an excimer laser having definable masking.

21. (Amended) The method according to claim 13, wherein the step of blunting includes the step of treating sectioned [sensing elements] composite arrangements with a laser, the sectioned [sensing elements] composite arrangements having a composition construction of green films.

22. (Amended) The method according to claim 21, further comprising the step of:

sectioning the [sensing element] composite arrangement from a wafer,